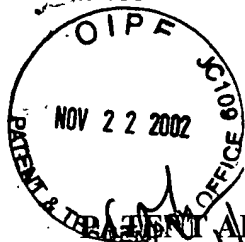


DIODATO 8-35-22



IN THE UNITED STATES
PATENT AND TRADEMARK OFFICE

PATENT APPLICATION

Inventors: Philip W. Diodato
Chun-Ting Liu
Ruichen Liu

Case 8-35-22

Serial No. 09/742,314

Group Art Unit 2815

Filed December 21, 2000

Examiner J.H. Nguyen

Title Inter-Wiring-Layer Capacitors

ASSISTANT COMMISSIONER FOR PATENTS
WASHINGTON, D.C. 20231

SIR:

Amendment

This reply is in response to the Official Action mailed July 15, 2002.

IN THE CLAIMS

1. (amended) An integrated circuit, comprising:
a semiconductor substrate including semiconductor devices;
a first wiring layer having an associated thickness being located over the substrate and having interconnect wire embedded therein;
a second wiring layer having an associated thickness being located on the first wiring layer and having interconnect wire embedded therein; and
a capacitor having a first metal-based charge-storage electrode, a second metal-based charge-storage electrode, and a dielectric layer interposed between the charge-storage electrodes, the charge-storage electrodes extending through the thickness of the second wiring layer and at least part of the first wiring layer wherein the capacitor is completely disposed in a window formed in the wiring layer.

#16/B
Amst
J. M. Cumilla
12/3/02
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TO 1700 MAIL ROOM
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TECHNOLOGY CENTER 2800